Supplementary Information for

The effect of oxidation states of supported oxides on catalytic activity: CO oxidation studies on Pt/cobalt oxide

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Experimental details

1.1 Atomic layer deposition of CoO_x on Si wafers.

Cobalt oxide (CoO_x) thin films were deposited by atomic layer deposition (ALD) on Si (100) wafers. The CoO_x films were deposited using a travelling-wave type ALD reactor (Lucida-D100, NCD Technology) with bis(1,4-di-iso-propyl-1,4-diazabutadiene)cobalt $[C_{16}H_{32}N_4Co, Co(dpdab)_2]$ and oxygen (O₂) as the precursor and reactant, respectively. One ALD cycle is made up of 10 s of Co precursor pulsing, 10 s of N₂ purging, and 10 s of oxygen reactant pulsing, followed by 10 s of N₂ purging to ensure self-limiting ALD growth of the CoO_x films. The Co precursor line was kept at 373 K to prevent any possible condensation of the precursor during the reaction. After every precursor and reactant pulse, 100 sccm of N₂ was injected into the ALD chamber as a purging gas to eliminate any residual chemicals and reaction by-products. The phase of the CoO_x film was then determined by the temperature in the ALD chamber. CoO_x films with CoO and Co₃O₄ phases are formed with deposition temperatures of 423 and 573 K were observed to be 0.039 and 1.13 nm/cycle, respectively. In this work, the thickness of all the ALD CoO_x films was set to about 55 nm.

1.2 Pt nanoparticle deposition on the SiO₂, CoO, and Co₃O₄ thin films via the Langmuir– Blodgett technique and arc plasma deposition.

Pt nanoparticles (PtNPs) were synthesized using one-pot polyol reduction and arc plasma deposition (APD) to investigate the effect of the organic capping agent on the interface between the metal and oxide thin films. First, the colloidal PtNPs were synthesized via the one-pot polyol reduction method. In detail, for the 1.9 nm PtNPs, 100 mg of H₂PtCl₆·6H₂O, and 5 mL of 0.5 M NaOH were dissolved in 10 mL of ethylene glycol (EG); this solution was refluxed at 433 K for 2 hours with argon purging. After that, 20.3 mg of poly(N-vinylpyrrolidone) (PVP, MW = 29,000) was added as a stabilizer. In the case of the 5.6 nm PtNPs, a solution of 120 mg of tetramethyl-ammonium bromide [N⁺(CH₃)4Br⁻], 20 mg of ammonium tetrachloroplatinate (II) [(NH₄)₂PtCl₆], 100 mg of PVP (MW = 29,000), and 10 mL of EG was heated at 453 K for 20 min. Using TEM analysis, the

size and topography of the 1.9 and 5.6 nm PtNPs were characterized (Fig. 1). Both the 1.9 and 5.6 nm PtNPs were diluted in 20 ml of ethanol and sonicated for 10 min to prepare the Pt suspension for the Langmuir-Blodgett process without drying. A chloroform solution of 750 μ L of the Pt suspension (Pt : chloroform = 1 : 1) was dropped on the water surface in the Langmuir–Blodgett trough (611 Nima Technology) at room temperature. The initial surface pressure was adjusted to zero before and after dropping the Pt suspension. A two-dimensional film of PtNPs on the prepared substrates was formed by compressing the layer of PtNPs on the water surface with a barrier speed of 10 cm²/min to the target surface pressures of 12 and 15 mN/m for the 1.9 and 5.6 nm PtNPs, respectively. The lifting rate of the substrate beneath the water was 1 mm/min. To prepare the non-capped Pt samples, a coaxial pulsed arc plasma deposition system (ULVAC, ARL-300) was used to deposit the PtNPs onto the three different metal oxides at room temperature under vacuum, *i.e.*, about 10^{-6} Torr. The size of the PtNPs can be manipulated by changing the arc voltage and the number of plasma pulses. To fabricate the 2 nm PtNPs, the arc voltage and the condenser capacity were set at 100 V and 1080, respectively. The number of plasma pulses was 30 shots.

Characterization

The size distribution and morphology of the synthesized PtNPs were evaluated using cross-section high resolution transmission electron microscopy (HR-TEM, Titan Cubed G2 60-300 (FEI)) and scanning transmission electron microscopy and high-angle annular dark field (STEM-HAADF, Titan Cubed G2 60-300 (FEI). The TEM samples were prepared by cutting cross sections of the 5.6 nm PtNPs on Co₃O₄ using the focused ion beam technique (FIB, Helios NanolabTM 450 F1). The morphology of the PtNPs on cobalt oxide catalysts was confirmed using scanning electron microscopy (SEM, Magellan 400 (FEI)). The chemical states of the platinum (Pt 4f) and cobalt oxide (Co 2p) were identified using X-ray photoelectron spectroscopy (XPS, Thermo VG Scientific Sigma Probe with an Al K α X-ray source (1486.3 eV)) with an energy resolution of 0.5 eV full width at half maximum under

ultra-high vacuum (10^{-10} Torr). All the binding energies were calibrated to the C 1s peak at 284.8 eV. The crystal structures of the CoO and Co₃O₄ thin films were revealed using Xray diffraction (Rigaku D/MAX 2500 at 40 kV, 300 mA) patterns with Cu K radiation over the 2O range of 10–80°.

CO oxidation and kinetics study

The catalytic performance was measured in an ultra-high vacuum chamber (1 L) with a base pressure of 10^{-8} Torr evacuated using rotary and turbo molecular pumps. After evacuation, reactant gases of 40 Torr of CO and 100 Torr of O₂ and 620 Torr of He as the balancing gas were filled into the batch chamber. The mixed gases in the reactor were circulated through the reaction line using a Metal Bellows recirculation pump (MB-41) at 2 L min⁻¹. To detect the reactants and products, a DS 6200 gas chromatograph was used with a thermal conductivity detector; a 6 ft. × 1/8 in. SS molecular sieve 5A was used to separate the reactants, *i.e.*, CO and O₂, and the product, *i.e.*, CO₂. The CO conversion was measured dependent on the reaction temperature (453–523 K). The reaction rates, *i.e.*, turnover frequencies (TOF), were obtained in units of CO₂ produced per Pt active surface site per reaction time (sec) as shown in the following equation:

Turnover frequency
$$(TOF) = \frac{Turnover num ber(TON)}{Reaction tin e} = \frac{(CO conversion) \times \frac{P_{CO}V}{RT} \times N_A}{Pt active surface site \times Reaction tin e}$$

All the reaction data were obtained at low conversion, *i.e.*, CO conversion less than 20%, presuming that the initial reaction rate was in a kinetically controlled regime. The number of Pt active sites was obtained from the surface areas of SEM images of the 1.9 and 5.6 nm PtNPs on CoO and Co₃O₄ (Fig. S3). For the APD Pt samples, we refer to reference (26). Kinetic experiments of CO oxidation on the 5.6 nm PtNPs on Co₃O₄ were performed at 513 K with a partial pressure of CO (3.2 ~ 160 Torr) with 100 Tor of O₂ and a partial pressure of O₂ (10 ~ 82 Torr) with 40 Torr of CO.



Fig. S1 SEM cross section images of the (a) CoO and (b) Co₃O₄ thin films fabricated via atomic layer deposition.



Fig. S2 XRD patterns and XPS spectra of Co 2p for the (a, c) CoO and (b, d) Co₃O₄ films.



Fig. S3 SEM images of the 1.9 and 5.6 nm PtNPs on (a, d) SiO_2 , (b, d) CoO, and (c, f) Co_3O_4 substrates.



Fig. S4 Kinetic study for CO oxidation on the 5.6 nm PtNPs supported on Co_3O_4 at 513 K as a function of (a) CO pressure and (b) O_2 pressure.



Fig. S5 XRD patterns of the 5.6 nm PtNPs on CoO and Co_3O_4 thin films (a, b) before and (c, d) after the CO oxidation reaction.



Fig. S6 XPS spectra of Co 2p for the CoO and Co_3O_4 thin films (a, c) before and (b, d) after the CO oxidation reaction.



Fig. S7 XPS spectra of Pt 4f for the 1.9 nm PtNPs on SiO₂, CoO, or Co₃O₄ thin films (a, b, c) before and (d, e, f) after the CO oxidation reaction.



Fig. S8 XPS spectra of Pt 4f for the 5.6 nm PtNPs on SiO₂, CoO, or Co₃O₄ thin films (a, b, c) before and (d, e, f) after the CO oxidation reaction.



Fig. S9 TOF and Arrhenius plot for CO oxidation on the CoO and Co₃O₄ substrates.